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(12) **United States Design Patent**
Masuda

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(54) **SEMICONDUCTOR DEVICE**

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(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
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CPC . H05K 1/0228; H05K 1/0245; H05K 1/0236;
H05K 1/0263; H01L 21/02433; H01L 29/04
See application file for complete search history.

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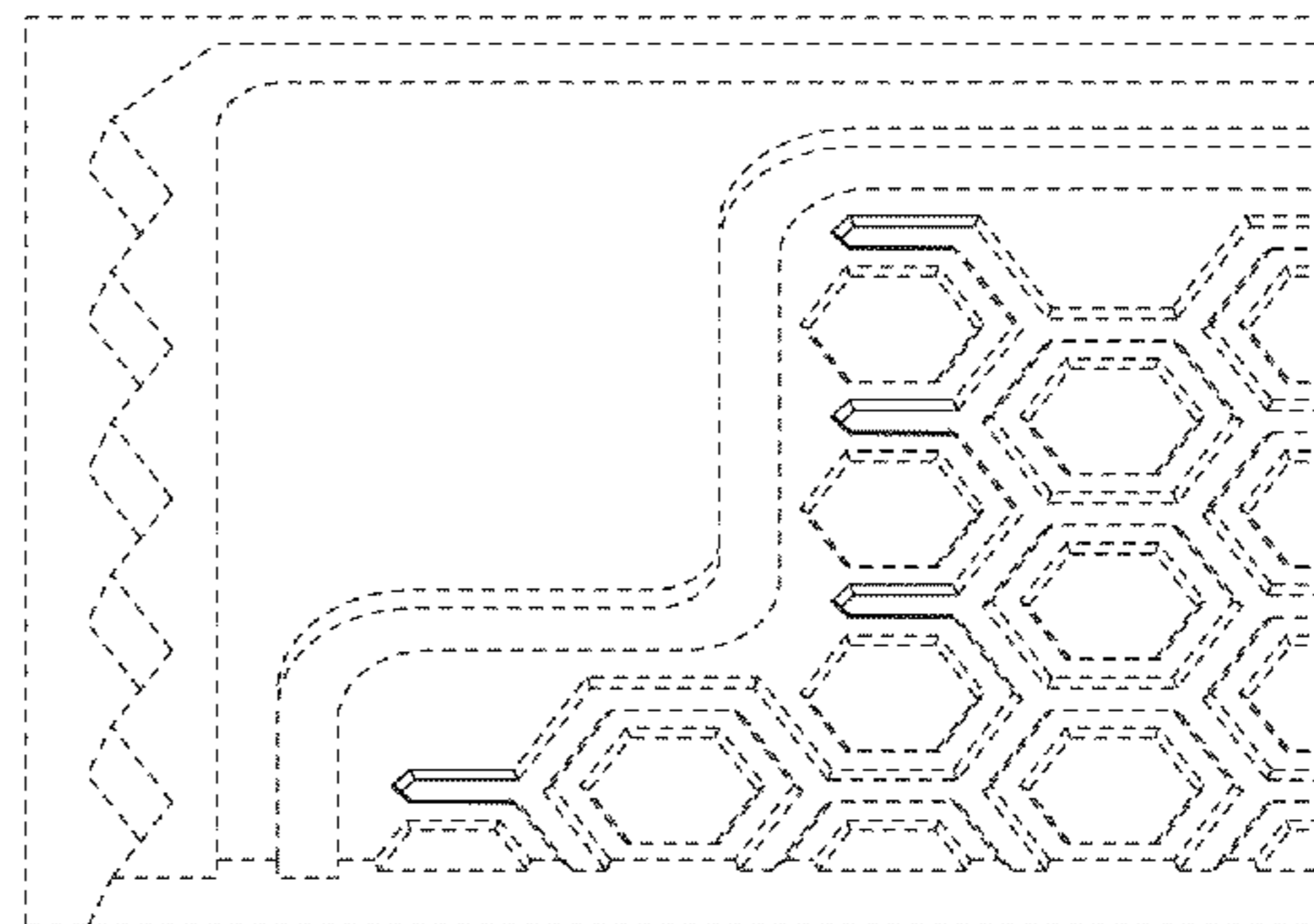
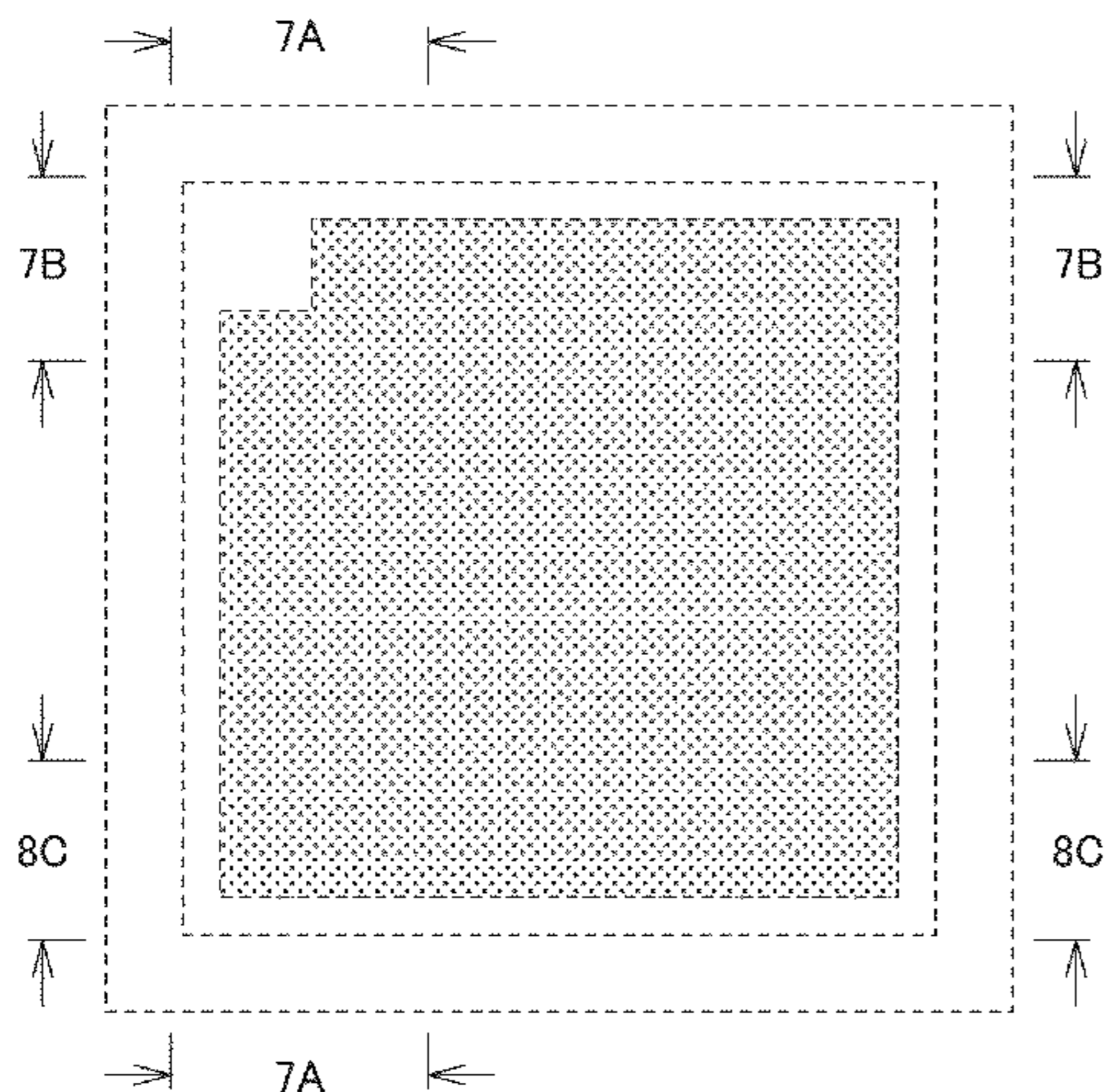
(57) **CLAIM**

The ornamental design for a semiconductor device, as shown and described.

DESCRIPTION

FIG. 1 is a front view of a semiconductor device showing my new design;
FIG. 2 is a rear view thereof;
FIG. 3 is a top plan view thereof;
FIG. 4 is a bottom plan view thereof;
FIG. 5 is a right side view thereof;
FIG. 6 is a left side view thereof;
FIG. 7 is an enlarged perspective view showing the area defined by indicia 7A and 7B of FIG. 1 thereof; and,
FIG. 8 is an enlarged perspective view showing the area defined by indicia 7A and 8C of FIG. 1 thereof.
The broken line showing is for illustrative purpose only and forms no part of the claimed design.

1 Claim, 4 Drawing Sheets



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FIG.1

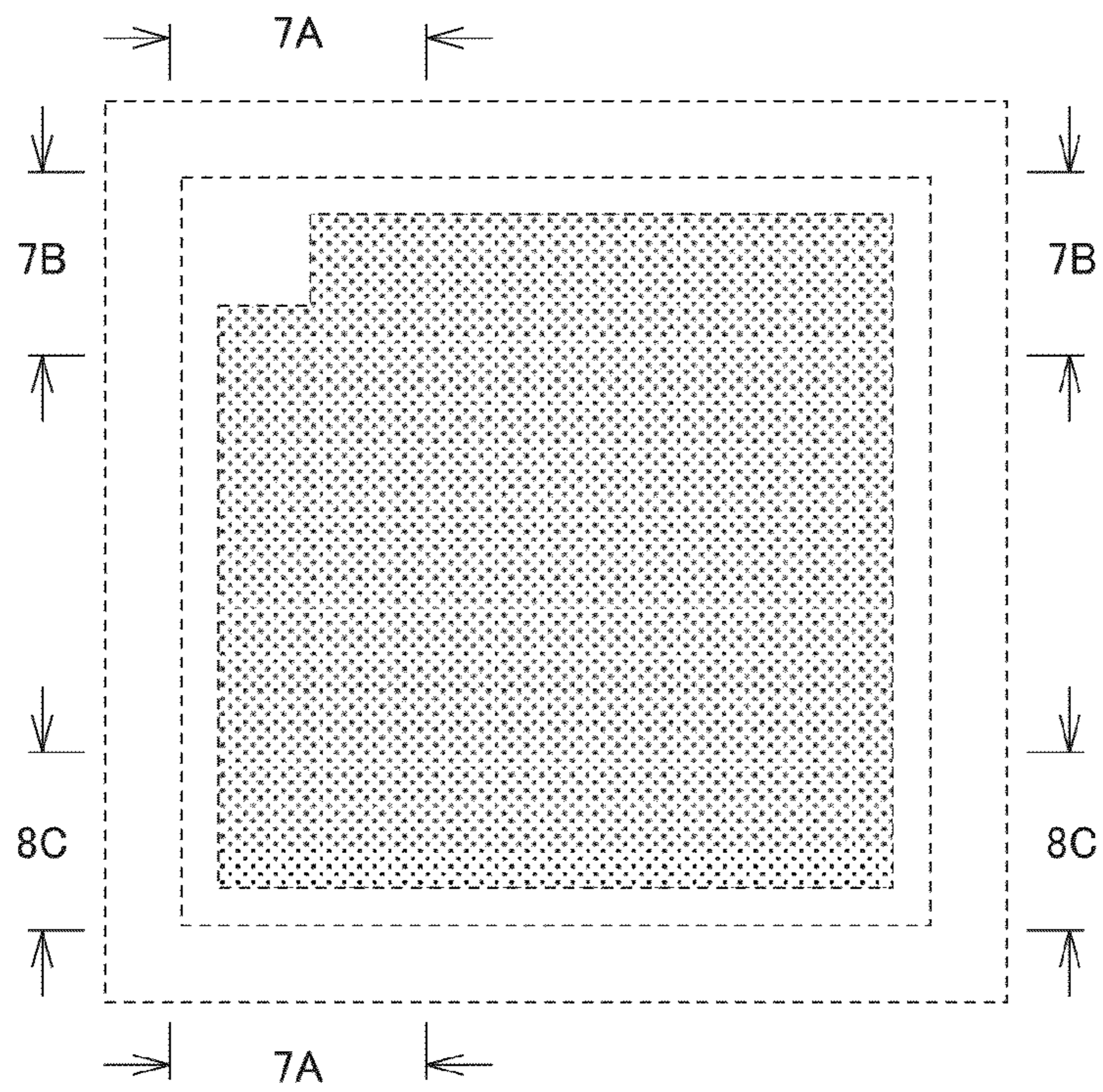


FIG.2



FIG.3



FIG.4



FIG.5



FIG.6



FIG.7

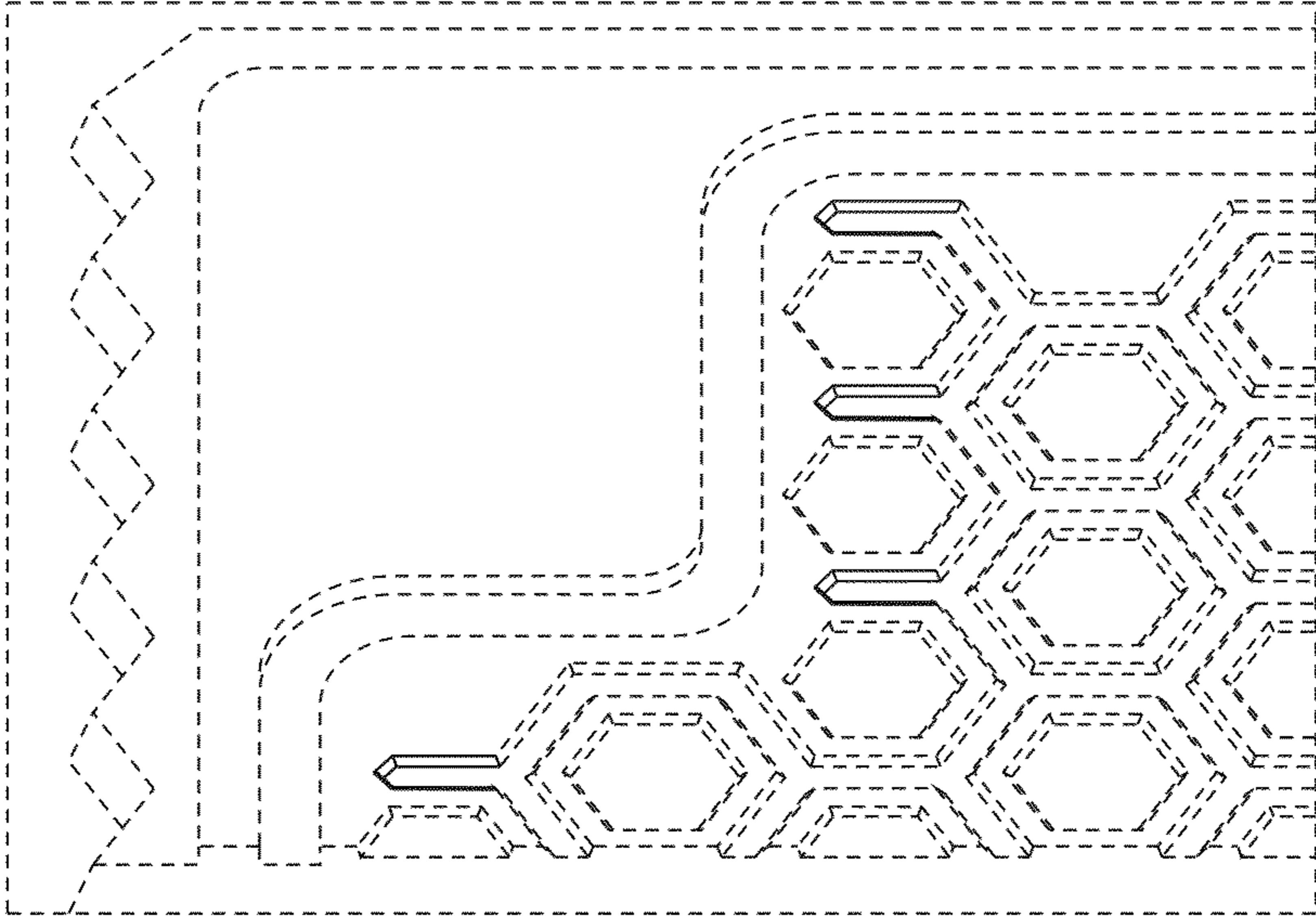


FIG.8

